Hologram Lasers GH6M005A5B

GH6M005A5B

Features

- (1) Super-thin package (3mm thickness) due to insert frame structure
- (2) Operating current Iop: TYP. 28mA

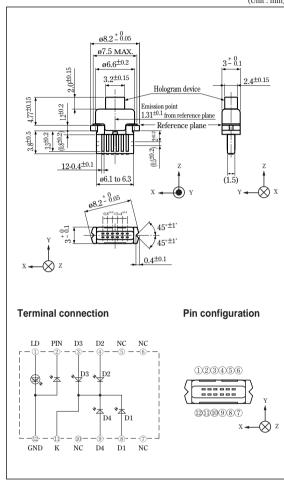
Applications

Playback only MD players

3mm Thickness Resin type Hologram Laser for Playback Only MD Player

Outline Dimensions

(Unit: mm)



Absolute Maximum Ratings

	Absolute Maximum Ratings								
	Parame	eter	Symbol	Rating	Unit				
*1	Optical power output	ıt	Рн	4.5	mW				
		Laser		2	V				
	Reverse voltage	Photodiode	V_R	30	V				
		Signal detection photodiode		15	V				
*2	Operating temperat	ture	Topr	-10 to +60	°C				
*2	Storage temperatur	e	Tstg	-40 to +85	°C				
#3	Soldering temperat	ure	Tsold	260	°C				

^{*1} Output power from hologram laser CW (Continuous Wave) drive

Case temperature

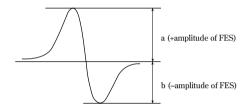
At the position of 1.6mm from the lead base (Within 5s)

■ Electro-optical Characteristics

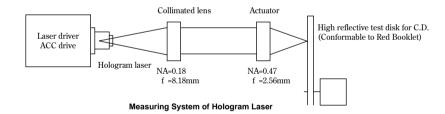
(Tc=25°C)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Focal offset	DEF		-0.5	-	+0.5	μm
*1 Focal error symmetry	Bres	C-11:	-15	-	+15	%
*2 Radial offset	-	Collimated lens output power PCL=1.1mW	80	-	120	%
*3 FES output amplitude	IFES	PCL=1.1mW -	2.0	4.2	6.1	μА
*4 Main spot balance	MSB		70	100	130	%
*5 Stray light	-	P _H =4mW	-	-	0.1	μA
Threshold current	Ith	_	1	20	30	mA
Operating current	Iop		5	28	40	mA
Operating voltage	Vop	P _H =2.7mW	-	1.9	2.2	V
Wavelength	λ_{p}		770	780	790	nm
Output current	Im	P _H =2.7mW, V _R =15V	0.001	-	0.2	mA
Differential efficiency	ηd	1.8mW I(2.7mW)-I(0.9mW)	0.2	0.6	1.0	mW/mA

^{*1 (}a-b) / (a+b)



- *2 D1 / D4 (focal servo ON)
- *3 D2–D3 (Focal vibration)
- **4 (D1+D4) / (D2+D3)
- Output of D2, D3 when hologram output is 4mW and outside light is cut off.



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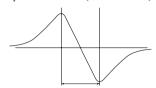
■ Electro-optical Characteristics of Hologram Laser (Design Standard*)

(Tc=25°C)

Parameter	Conditions	MIN.	TYP.	MAX.	Unit
*1 RF output amplitude		5	8.4	-	μA
*2 RES output amplitude	Pci=1.1mW	1	2	3.5	μА
*3 Focal error signal capture range	PCL=1.1mw	-	19	-	μm
*4 Focal error noise		-7	-	+7	%
Space between main and sub beam	Disc surface	-	19.7	-	μm

^{*1} Amplitude of D1+D2+D3+D4 (focal servo ON, radial servo ON)

***3**





■ Optical Characteristics of Hologram Device (Design Standard*)

(Tc=25°C)

Parameter	Conditions	MIN.	TYP.	MAX.	Unit
Transmissive wave aberration	_	-	-	λ/8	-
Surface parallelism	-	-	-	5	min.
Hologram diffraction efficiency (0:1)		-	80:8	-	%
Grating diffraction intensity ratio (0:1)	$\lambda_p = 780 nm$	9:1	10.5:1	12:1	-
Grating diffraction intensity ratio (+1:-1)	ty ratio (+1 : -1)		1	1.1	-
Grating rotation angle	to hologram parting line	-	1.16	-	۰

■ Electro-optical Characteristics of Laser Diode (Without Hologram Device) (Design Standard*)

(Tc=25°C)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit	
Half intensity angle Pe		Parallel	θ//	Do. 2mW	9	-	18	۰
		Perpendicular	θΤ		28	-	45	۰
Emission	Deviation	Parallel	ø//	Po=3mW	-2	-	+2	۰
characteristics	angle	Perpendicular	ø⊥		-3	-	+3	۰
Misalignment position		ΔX, Y, Z	_	-80	-	+80	μm	
Kink		LKink		-15	-	+15	%	
Interference pattern intensity		α	Po=3mW	1	-	0.95	-	
Chip thickness			-	Active layer to chip edge	-	-	55	μm

■ Electrical Characteristics of Monitor Photodiode (Design Standard*)

(Tc=25°C)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Dark current	ID	V- 15V	-	-	150	nA
Terminal canacitance	Ct	V _R =15V	_	9	_	ρF

■ Electro-optical Characteristics of Photodiode for Signal Detection (Design Standard*)

(Tc=25°C)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Reverse voltage		V_R	Ir=10µA	12.5	-	50	V
Terminal capacitance	D2, D3	Ct	V _R =12.5V, f=1MHz	1.2	-	5	pF
Terminai capacitance	D1, D4			1.4	-	5.8	
Sensitivity		S	$\lambda_p=780 nm$	0.4	0.5	0.65	A/W
Response time	D2, D3	tr. tf	V _R =15V, R _L =180Ω	-	10	120	
Response time	D1, D4	u, u		-	10	200	ns

^{*} These parameters are not guaranteed performance, but general specifications of each optical element which makes up a hologram laser.

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^{*2} Amplitude of D1–D4 (focal servo ON)

[•] Please refer to the chapter "Handling Precautions"

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